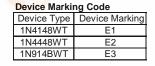


March 2008

1N4148WT / 1N4448WT / 1N914BWT **High Conductance Fast Switching Diode**

- Fast Switching Diode (Trr <4.0nsec)
- Flat Lead, Surface Mount Device under 0.70mm Height
- Extremely Small Outline Plastic Package SOD523F
- Moisture Level Sensitivity 1
- Pb-free Version and RoHS Compliant
- Matte Tin (Sn) Lead Finish
- Green Mold Compound







SOD-523F **Band Indicates Cathode***

Absolute Maximum Ratings* Ta=25°C unless otherwise noted

Symbol	Parameter	Value	Units	
V _{RSM}	Non-Repetitive Peak Reverse Voltage	75	V	
V _{RRM}	Repetitive Peak Reverse Voltage	75	V	
I FRM	Repetitive Peak Forward Current	300	mA	
TJ	Operating Junction Temperature Range	-55 to +150	°C	
T _{STG}	Storage Temperature Range	-55 to +150	°C	

^{*} These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	500	°C/W
P _D	Power Dissipation(T _C =25°C)	200	mW

^{*}Device mounted on FR-4 PCB minimum land pad.

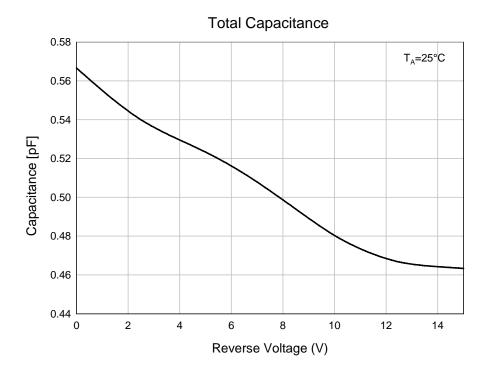
Electrical Characteristics* T_a=25°C unless otherwise noted

Symbol	Param	eter	Test Conditions	Min	Тур	Max	Units
BV_R	Breakdown Voltage	-TP LCOM	I _R = 100 μA I _R = 5 μA	100 75			V
I _R	Reverse Current	4.0-	V _R = 20 V V _R = 75 V			25 5	nA μA
V _F	Forward Voltage	1N4448WT/ 914WT 1N4448WT 1N4448WT/ 914WT	$I_F = 5 \text{ mA}$ $I_F = 10 \text{ mA}$ $I_F = 100 \text{ mA}$	0.62		0.72 1 1	V
Co	Diode Capacitance		V _R = 0, f = 1 MHz			4	pF
T _{RR}	Reverse Recovery Time		$I_F = 10 \text{ mA}, V_R = 6.0 \text{ V}$ $I_{RR} = 1 \text{ mA}, R_L = 100 \Omega$			4	nS

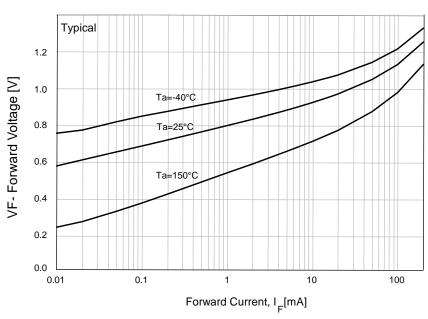
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¹⁾ These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

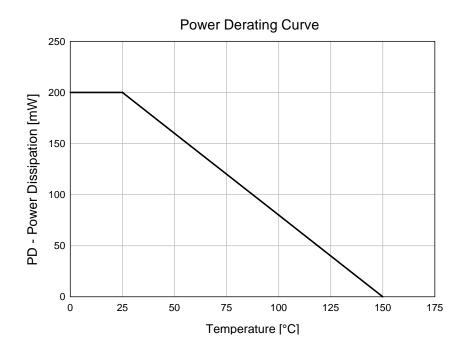
Typical Performance Characteristics

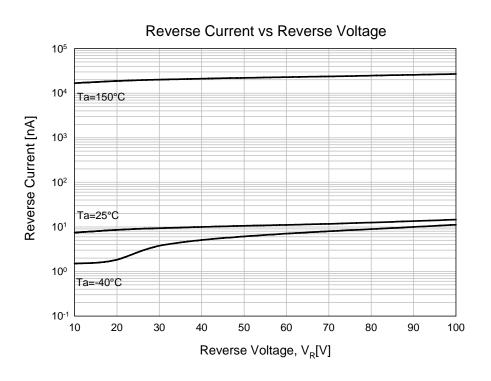


Forward Voltage vs Ambient Temperature

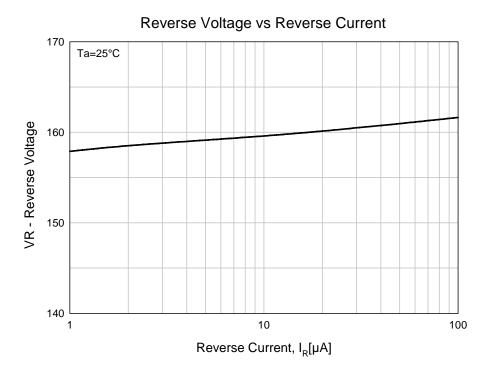


Typical Performance Characteristics



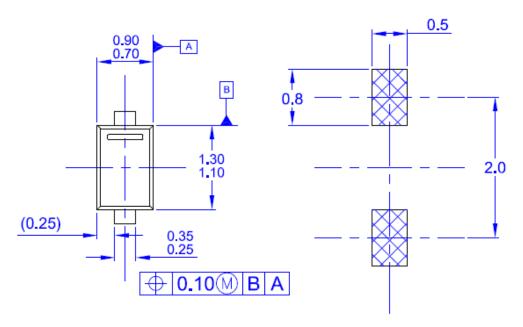


Typical Performance Characteristics

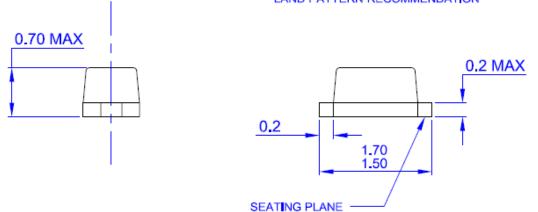


Package Dimension

SOD-523F



LAND PATTERN RECOMMENDATION



NOTES: UNLESS OTHERWISE SPECIFIED

- A) PACKAGE REFERENCE: THIS PACKAGE OUTLINE CONFORMS TO JEITA SC-79.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DRAWING CONFORMS TO ASME Y14.5M 1994
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) LANDPATTERN RECOMMENDATION IS BASED ON IPC7351A STANDARD SOD1609X65M.
- F) DRAWING NUMBER AND REVISION;MKT-SOD523F1rev1





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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.
Obsolete	Not In Production	This datasheet contains specifications on a product that has been discontinued by Fairchild semiconductor. The datasheet is printed for reference information only.

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